

Composite Fins for Heat Sinks

Abstract of the Disclosure

A heat sink that dissipates heat from an electronic device. The heat sink
5 includes a base that is adapted to be thermally coupled to the electronic device, and
a fin that is thermally coupled to the base. The fin includes a first portion made
from a first material and a second portion made from a second material. One edge
of the first portion and an opposing edge of the second portion form at least one of a
lap joint and a butt joint between the first portion and the second portion. In some
10 forms, the first portion of the fin is a copper portion that is thermally coupled to a
copper base to conduct thermal energy away from the base, and the second portion
of the fin is aluminum.

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